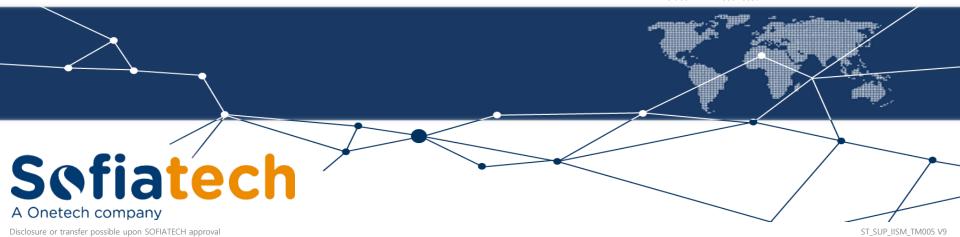
### Neoxa 3

### **Project Approach**

Reference: HBS\_PNXA\_DP003

Version: 2.0
Date: 09/07/2025
Author: JKEB/AGHR
Class: D - Restricted



### **Project Scope**



#### Neoxa 3

- Neoxa 3 is the upgraded version of the previous Neoxa 2.
- The main goal is to improve the current version by addressing its limitations and the areas needing some improvement.
- What Neoxa 3 adds compared to Neoxa 2:
  - Mechanical enhancement: miniaturized design and wireless setup,
  - **New features**: PPG sensing (in addition to EEG), on-board processing and bone conduction audio (to be confirmed),
  - **System optimization and hardening**: reliable connectivity (BLE), robust sensing (signal quality), energy efficiency
- Project deadline: December 2025 (5 prototypes)
- Next big milestone: CES 2026

## Technical challenges

### Sofiatech

### **Design considerations for Neoxa 3**

#### **Mechanical aspects:**

- Form factor (size)
- Ergonomics and comfort of use
- Choice of materials

#### **Functional aspects:**

- BLE connectivity
- EEG/PPG sensing
- Signal processing (features extraction, filtering, ...)
- Data processing (compression, formatting, storage, ...)

#### Non-functional aspects:

- Signal quality (signal noise, motion impact, interference)
- Communication reliability (range, throughput, latency, security)
- Power management (components selection, battery selection, operating modes, ...)



#### Prioritized:

- Optimization ↗
- Reliability and Robustness ↗
- Energy consumption ≥

#### 

- Average performance →
- Average responsiveness →
- Memory usage ✓

#### To keep in mind:

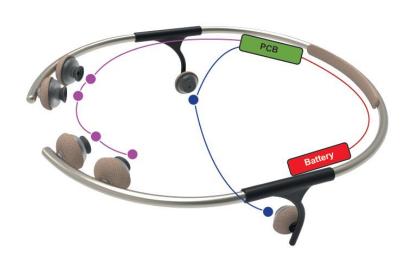
- Portability
- Maintainability
- Scalability

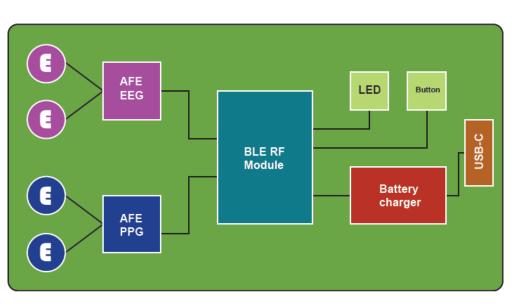


### **Preliminary Architecture\***



\*: To Be Confirmed Post-Analysis/Detailed Design





How many EEG electrodes should be used? How many PPG electrodes should be used? Are EEG and PPG signals acquired simultaneously?

### **Preliminary Technical Choices\***



\*: To Be Confirmed Post-Analysis/Detailed Design

#### **Hardware components:**

- MCU → NXP NHS52504 (Evaluation Kit: NHS52S04EVK \$412.00)
- EEG AFE → TI ADS1299 (Evaluation Kit: ADS1299EEGFE-PDK \$199.00)
- PPG AFE → <u>AD MAX86176</u> (Evaluation Kit: MAX86176EVKIT \$170,13)

#### **Software components:**

- Sensor drivers (Serial driver, EEG driver, PPG driver)
- Filtering and noise reduction algorithm
- Memory management (Embedded filesystem)
- BLE stack + Custom Profile for EEG/PPG data
- RTOS (for system orchestration)



Since we're still in the prototyping phase, we'll skip the RF certification for now. This can be handled later for the final design of the product.

# NHS52S04: Ultra-Low-Power Bluetooth® Low Energy Solution With Arm® Cortex®-M33 TrustZone® for Medical IoT



NHS52S04 Receive alerts @



Ultra-Low Power / Optimized for Medical IoT / Integrated Security / Small Form Factor / BLE 5.3 / Direct Battery Support / 3 FlexComm interfaces









Low Noise / Multiple Channels / SPI and I2C interfaces / Low Power Consumption



20 Waxim

Analog Devices / Maxim Integrated MAX86176 PPG and ECG Analog Front-End (AFE)

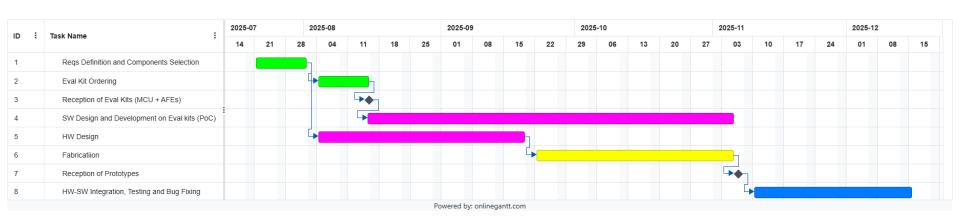


Dedicated PPG AFE / Designed for Wearable Applications / SPI interface / Low Power Consumption

# **Preliminary Project Timeline**



### **Assumptions & Constraints**



| Milestone                                 | Date       | Risk                                                                                        | Impact/Mitigation Plan                                                                                                      |
|-------------------------------------------|------------|---------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|
| Start of Work                             | 07/07/2025 | -                                                                                           | -                                                                                                                           |
| Reception of Evaluation Kits (MCU + AFEs) | 01/08/2025 | Delayed reception of Eval Kits                                                              | Project overtime / Allocate enough time (10 days) for shipment process                                                      |
| Reception of Prototypes                   | 24/10/2025 | HW Design delay due to mechanical constraints<br>Signal issues for EEG and PPG on prototype | Project overtime / Synchronization meetings with OVA Design<br>Non-useful prototype / Bypass the PPG AFE by hardware design |
| End of Work                               | 01/12/2025 | _                                                                                           | _                                                                                                                           |

### **Project organization**



We propose to mange the project with several successive packages:

Package 1: Requirements definition and components selection

Objectives: Co-design workshops to define priority functionalities and requirements and establishment of the product backlog.

Package 2: Design and Development (HW and SW) and FAB

Objectives: Design of the HW and development of the SW POC on eval kits.

Package 3: Integration, Validation and Bug fixing

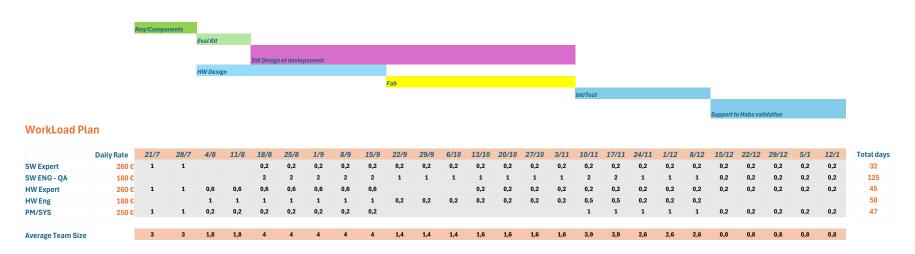
Objectives: Finalization of the solution and final testing.

The estimation of the project workload is not possible in this stage of the project. We suggest to proceed in a man and material model.

### **Workload and Cost Estimation**



Based on the schedule and the phases of the project, we estimate the following workload plan:



We estimate that the cost of the project would be around 63 K€.

We will proceed with monthly cost actual invoicing based on a timesheet shared monthly with the client.



# Thank you



